● General Description

The AGMH022P10A combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$

This device is ideal for load switch and battery protection applications.

● Features

- Advance high cell density Trench technology
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance
- 100% Avalanche tested
- 100% DVDS tested

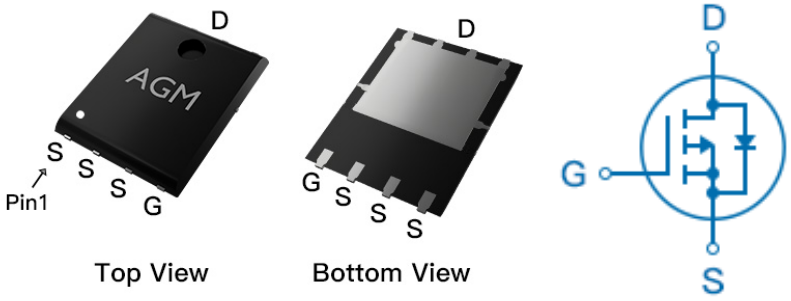
● Application

- MB/VGA Vcore
- SMPS 2nd Synchronous Rectifier
- POL application
- BLDC Motor driver

Product Summary

BVDSS	RDSON	ID
-100V	14mΩ	-65A

PDFN5*6 Pin Configuration



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
AGMH022P10A	AGMH022P10A	PDFN5*6	330mm	12mm	3000

Table 1. Absolute Maximum Ratings (TA=25℃)

Symbol	Parameter	Value	Unit
VDS	Drain-Source Voltage (VGS=0V)	-100	V
VGS	Gate-Source Voltage (VDS=0V)	±20	V
ID	Drain Current-Continuous(Tc=25℃) **(Note 1)**	-65	A
	Drain Current-Continuous(Tc=100℃)	-41	A
IDM (pluse)	Drain Current-Pulsed **(Note 2)**	-260	A
PD	Maximum Power Dissipation(Tc=25℃)	140	w
	Maximum Power Dissipation(Tc=100℃)	56	w
EAS	Avalanche energy **(Note 3)**	558	mJ
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 150	℃

Table 2. Thermal Characteristic

Symbol	Parameter	Typ	Max	Unit
RθJA	Thermal Resistance Junction-ambient (Steady State)[1]	---	20	℃/W
RθJC	Thermal Resistance Junction-Case[1]	---	0.89	℃/W

Table 3. Electrical Characteristics (TJ=25℃unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BV_{DSS}	Drain-Source Breakdown Voltage	VGS=0V ID=-250μA	-100	--	--	V
IDSS	Zero Gate Voltage Drain Current	VDS=-100V,VGS=0V	--	--	-1	μA
IGSS	Gate-Body Leakage Current	VGS=±20V,VDS=0V	--	--	±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	VDS=VGS,ID=-250μA	-2.0	-3.0	-4.0	V
gFS	Forward Transconductance	VDS=5V,ID=-5A	--	18	--	S
$R_{DS(on)}$	Drain-Source On-State Resistance	VGS=-10V, ID=-10A	--	14	24	mΩ
Dynamic Characteristics						
Ciss	Input Capacitance	VDS=40V,VGS=0V, F=1MHZ	--	4276	--	pF
Coss	Output Capacitance		--	336	--	pF
Crss	Reverse Transfer Capacitance		--	25	--	pF
Rg	Gate resistance	f=1.0MHz	--	2.9	--	Ω
Switching Times						
td(on)	Turn-on Delay Time	VGS=-10V,VDS=-50V, ID=-20A,RGEN=5Ω	--	15	--	nS
tr	Turn-on Rise Time		--	18	--	nS
td(off)	Turn-Off Delay Time		--	50	--	nS
tf	Turn-Off Fall Time		--	19	--	nS
Qg	Total Gate Charge	VGS=-10V, VDS=-50V, ID=-20A	--	52	--	nC
Qgs	Gate-Source Charge		--	17	--	nC
Qgd	Gate-Drain Charge		--	7.0	--	nC
Source-Drain Diode Characteristics						
ISD	Source-Drain Current(Body Diode)		--	--	-65	A
VSD	Forward on Voltage	VGS=0V,IS=-10A	--	--	-1.2	V
trr	Reverse Recovery Time	Isd=-10A , dI/dt=100A/μs , TJ=25℃	--	55	--	ns
Qrr	Reverse Recovery Charge		--	102	--	nc

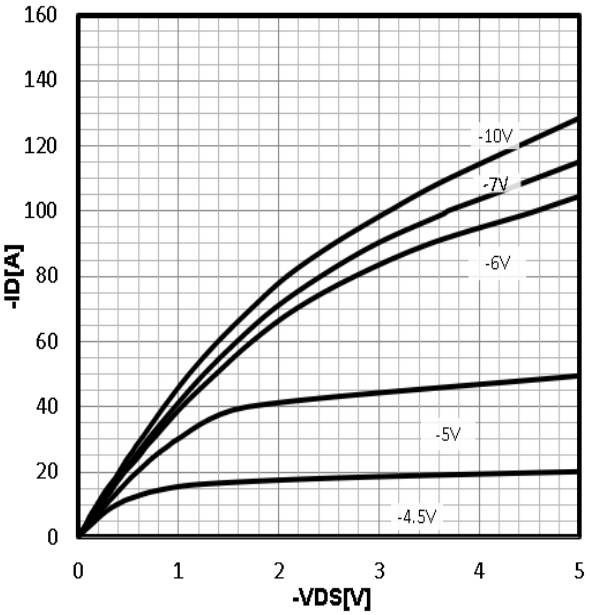
Notes 1.The maximum current rating is package limited.

Notes 2.Repetitive Rating: Pulse width limited by maximum junction temperature.

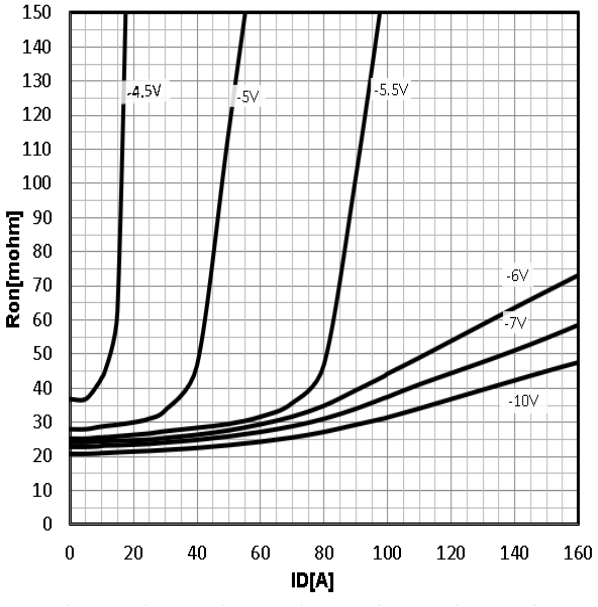
Notes 3.EAS condition: TJ=25℃,VDD=-50V,Vgs=-10V,ID=-61A,L=0.3mH,RG=25ohm

Characteristics Curve:

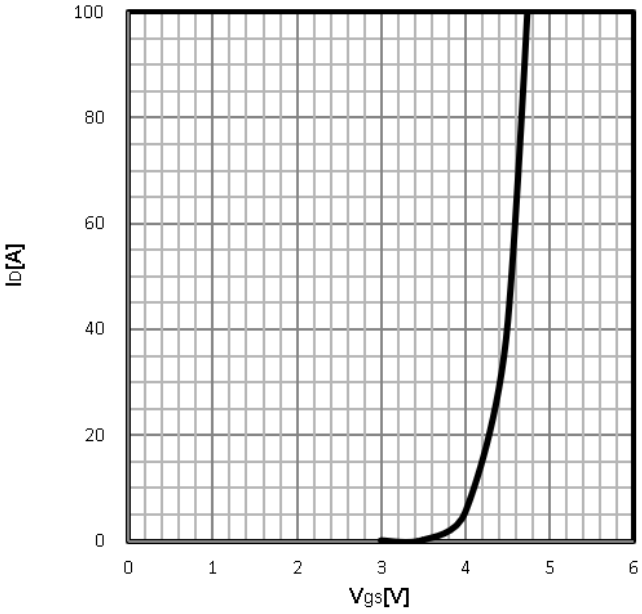
Typ. output characteristics
$-I_D=f(-V_{DS})$



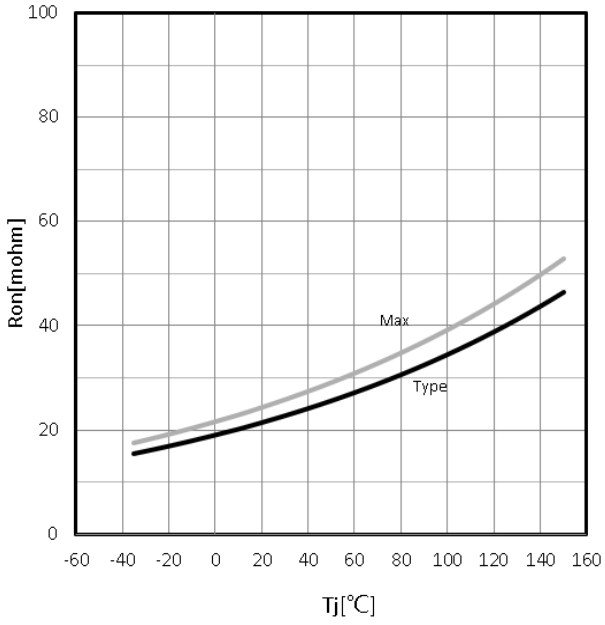
Typ. drain-source on resistance
$R_{DS(on)}=f(-I_D)$



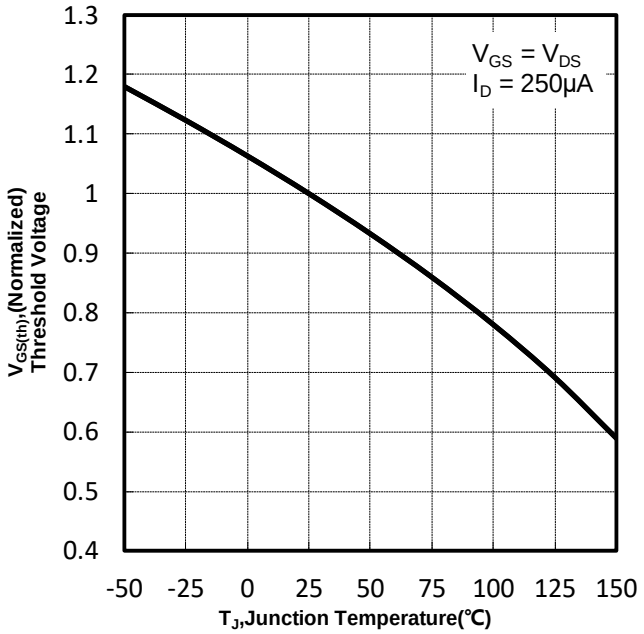
Typ. transfer characteristics
$-I_D=f(-V_{GS})$



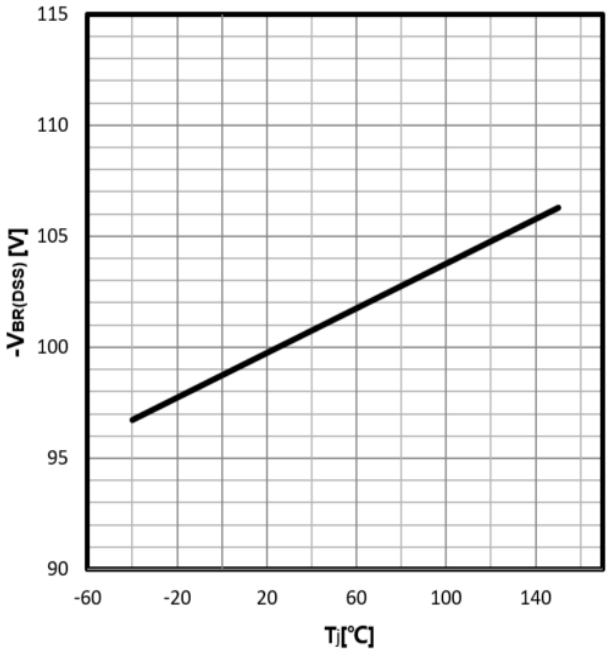
Drain-source on-state resistance
$R_{DS(on)}= f(T_j)$; I_D=-10A; V_{GS}=-10V



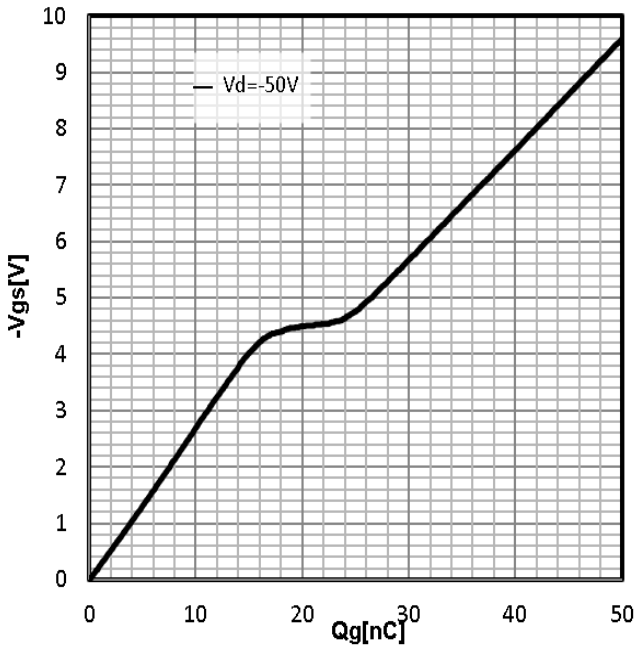
Gate Threshold Voltage
$-V_{TH}=f(T_j)$; I_D=-250uA



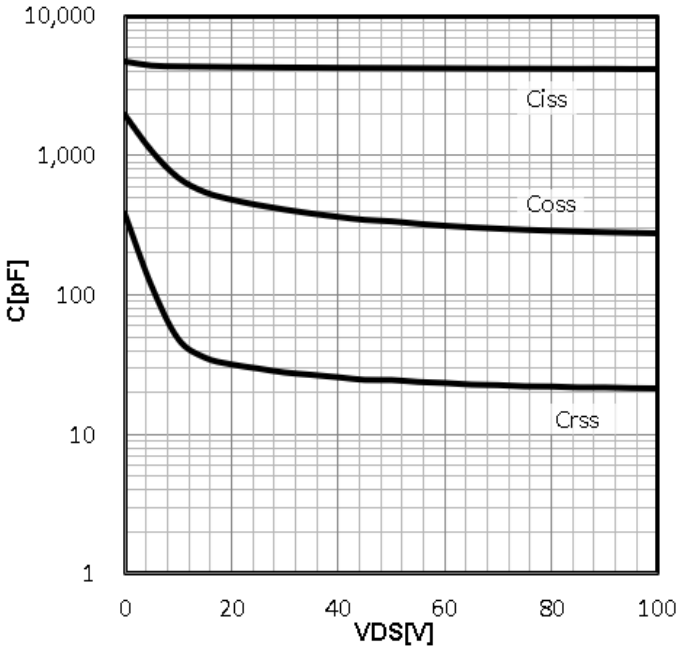
Drain-source breakdown voltage
$-V_{BR(DSS)}=f(T_j)$; I_D=-250uA



Typ. gate charge
$-V_{GS}=f(Q_g)$; I_D=-20A

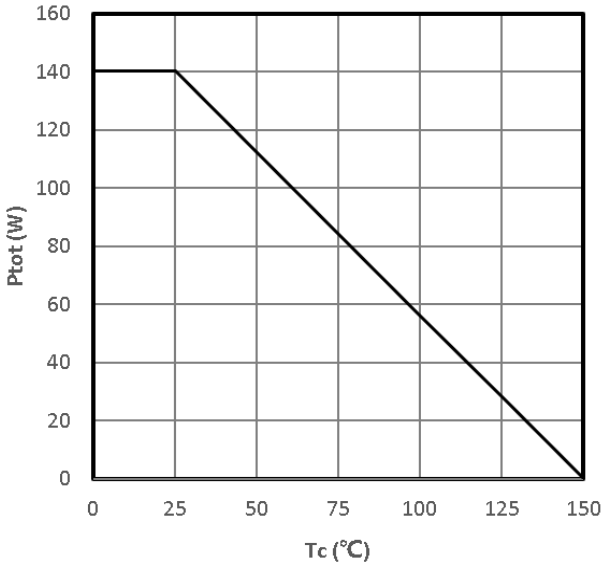


Typ. capacitances
C =f(-V_{DS}); V_{GS}=0V; f =1MHz



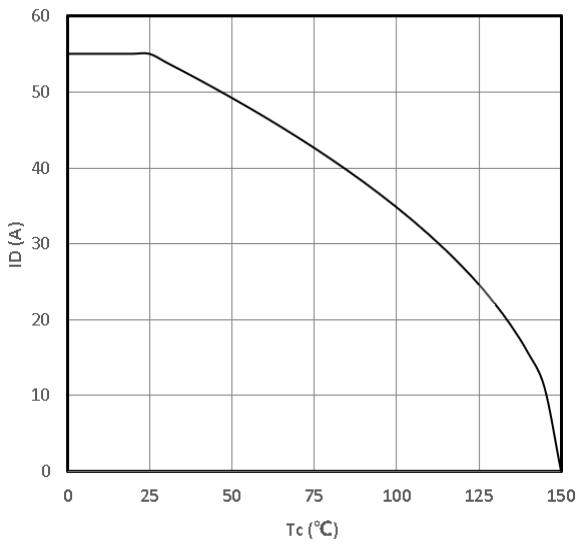
Power Dissipation

$P_{tot}=f(T_C)$



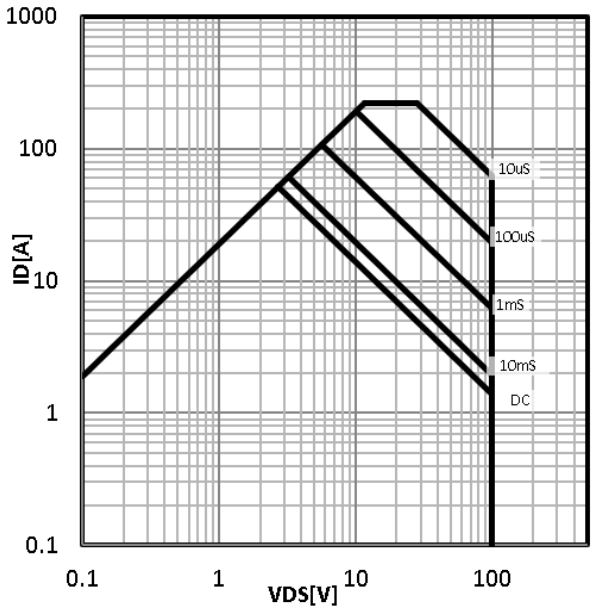
Maximum Drain Current

$-I_D=f(T_C)$



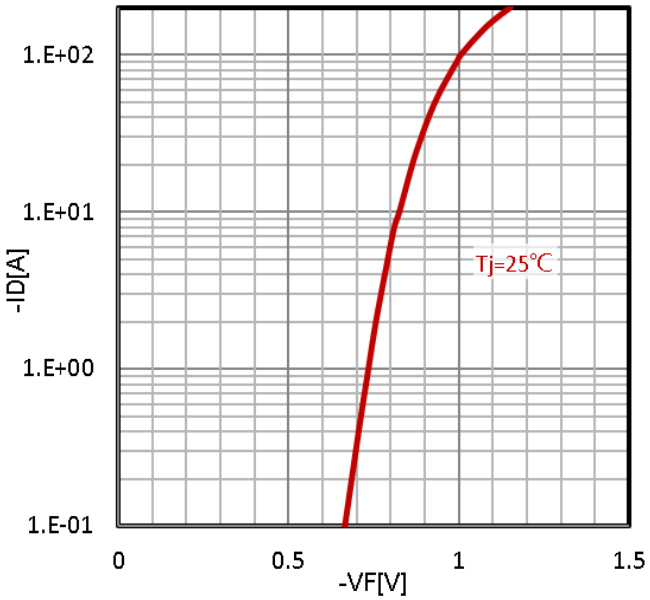
Safe operating area

$-I_D=f(-V_{DS})$



Body Diode Forward Voltage Variation

$-I_F=f(-V_{DS})$



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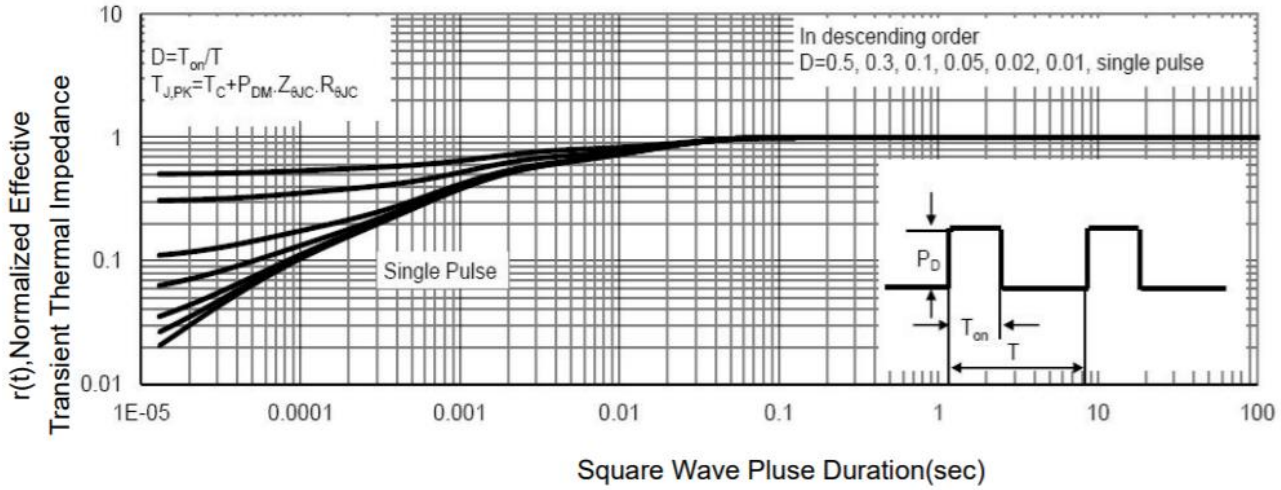
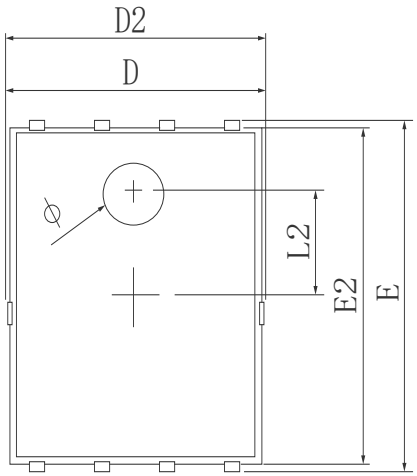
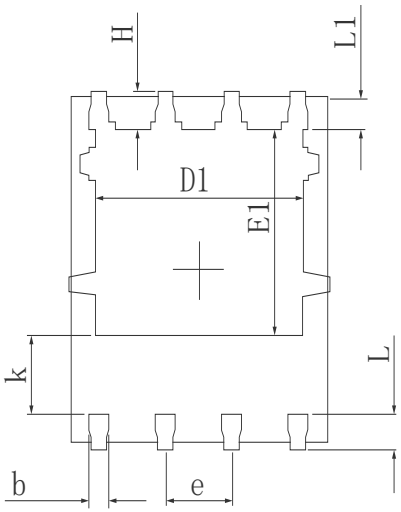
Max. transient thermal impedance

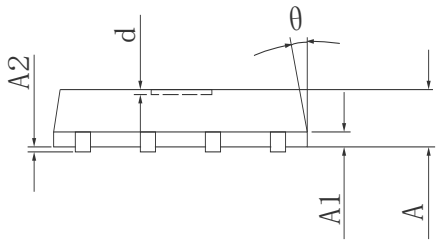
$Z_{thJC}=f(t_p)$



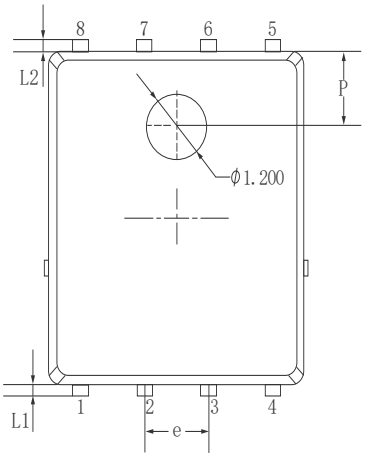
●Dimensions（PDFN5*6）

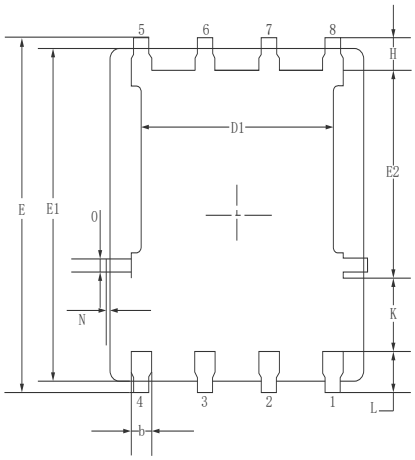


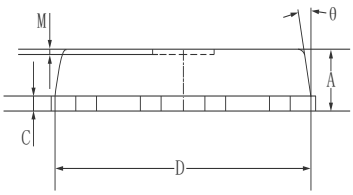




SYMBOL	MILLIMETER		
	MIN	Typ.	MAX
A	0.900	1.000	1.100
A1	0.254 REF.		
A2	0~0.05		
D	4.824	4.900	4.976
D1	3.910	4.010	4.110
D2	4.924	5.000	5.076
E	5.924	6.000	6.076
E1	3.375	3.475	3.575
E2	5.674	5.750	5.826
b	0.350	0.400	0.450
e	1.270 TYP.		
L	0.534	0.610	0.686
L1	0.424	0.500	0.576
L2	1.800 REF.		
k	1.190	1.290	1.390
H	0.549	0.625	0.701
θ	8°	10°	12°
Φ	1.100	1.200	1.300
d			0.100





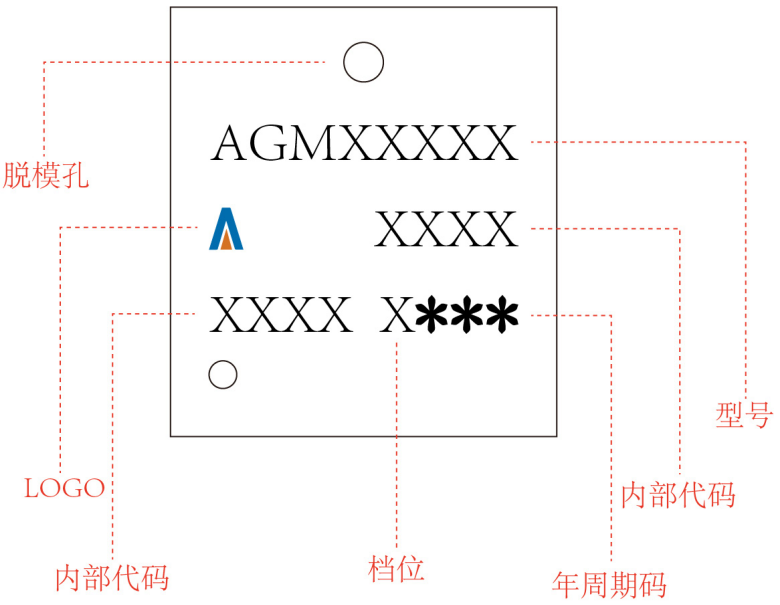


Symbol	Millimeters		
	MIN.	NOM.	MAX.
A	0.90	1.05	1.20
b	0.35	0.40	0.50
C	0.20	0.25	0.35
D	4.90	5.05	5.20
D1	3.72	3.82	3.92
E	6.00	6.15	6.30
E1	5.60	5.75	5.90
E2	3.47	3.57	3.67
e	1.27 BSC.		
H	0.48	0.58	0.68
K	1.17	1.27	1.37
L	0.64	0.74	0.84
L1/L2	0.20 REF.		
θ	8°	10°	12°
M	0.08 REF.		
N	0	-	0.15
O	0.25 REF.		
P	1.28 REF.		

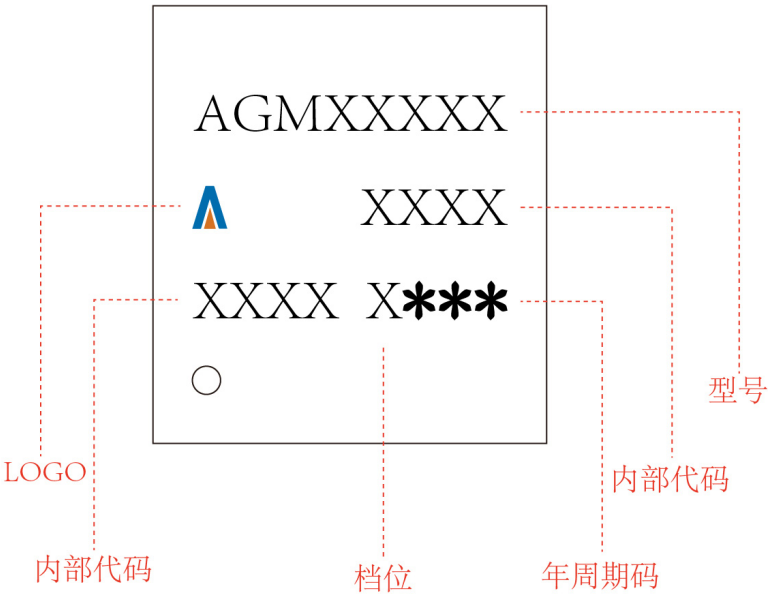
PDFN5*6

Marking Instructions:

Model1:



Model2:



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